## **DB3J314F**

## Silicon epitaxial planar type

For high speed switching circuits DB3X314F in SMini3 type package

#### ■ Features

- Short reverse recovery time t<sub>rr</sub>
- Small reverse current I<sub>R</sub>
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

#### ■ Marking Symbol: 5C

#### ■ Basic Part Number

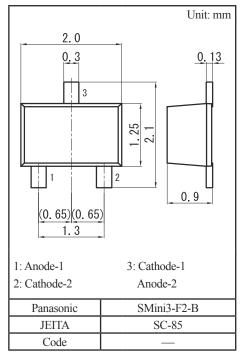
Dual DB2J314 (Series)

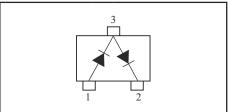
#### Packaging

DB3J314F0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter                     |        | Symbol           | Rating      | Unit |
|-------------------------------|--------|------------------|-------------|------|
| Reverse voltage               |        | V <sub>R</sub>   | 30          | V    |
| Maximum peak reverse voltage  |        | V <sub>RM</sub>  | 30          | V    |
| Forward current               | Single | ī                | 30          | mA   |
|                               | Series | - I <sub>F</sub> | 20          | mA   |
| Peak forward current          | Single | T                | 150         | mA   |
|                               | Series | $I_{FM}$         | 110         | mA   |
| Junction temperature          |        | T <sub>j</sub>   | 125         | °C   |
| Operating ambient temperature |        | T <sub>opr</sub> | -40 to +85  | °C   |
| Storage temperature           |        | T <sub>stg</sub> | -55 to +125 | °C   |

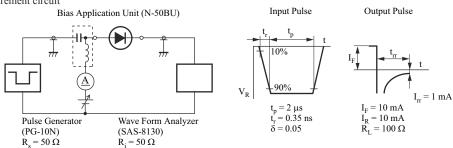


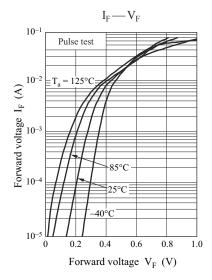


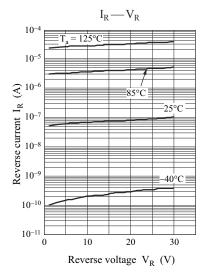
## ■ Electrical Characteristics $T_a = 25$ °C±3°C

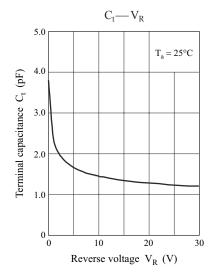
| Parameter                | Symbol          | Conditions   | Min | Тур | Max | Unit |
|--------------------------|-----------------|--|-----|-----|-----|------|
| Forward voltage          | $V_{F1}$        | $I_F = 1 \text{ mA}$   |     |     | 0.4 | V    |
|                          | $V_{F2}$        | $I_F = 30 \text{ mA}$  |     |     | 1.0 |      |
| Reverse current          | $I_R$           | $V_R = 30 \text{ V}$   |     |     | 300 | nA   |
| Terminal capacitance     | C <sub>t</sub>  | $V_R = 10 \text{ V}, f = 1 \text{ MHz}$                              |     | 1.5 |     | pF   |
| Reverse recovery time *1 | t <sub>rr</sub> | $I_F = I_R = 10 \text{ mA}, I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$ |     | 1.0 |     | ns   |

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. Absolute frequency of input and output is 2 GHz
    - \*1: t<sub>rr</sub> measurement circuit





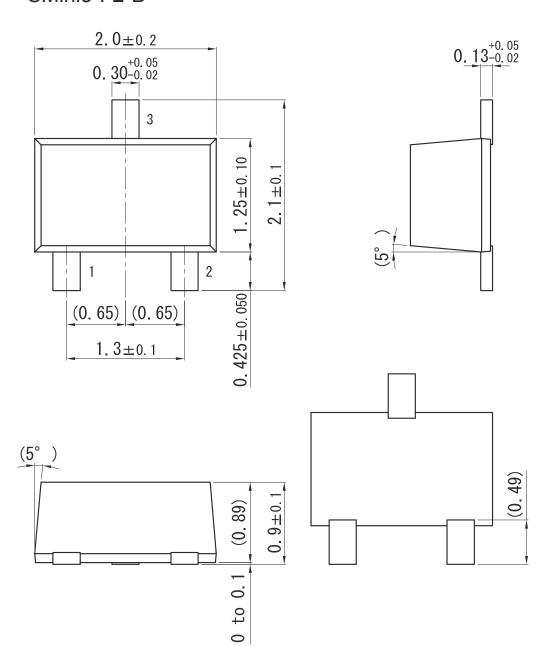




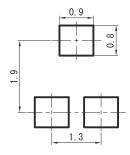
Ver. CED 2

## SMini3-F2-B

Unit: mm



### ■ Land Pattern (Reference) (Unit: mm)



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